PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT6223541

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
LIN ZHANG	01/08/2020
HUO YUN DUAN	01/08/2020
XI LIN LI	01/08/2020
CHEN XIONG	01/08/2020

RECEIVING PARTY DATA

Name:	TEXAS INSTRUMENTS INCORPORATED
Street Address:	12500 TI BOULEVARD
Internal Address:	MS 3999
City:	DALLAS
State/Country:	TEXAS
Postal Code:	75243

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	16941701

CORRESPONDENCE DATA

Fax Number: (214)567-2228

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 214-479-1230
Email: uspto@ti.com
Correspondent Name: TEXAS INSTRUMENTS INCORPORATED
Address Line 1: P O BOX 655474, MS 3999
Address Line 4: DALLAS, TEXAS 75265

ATTORNEY DOCKET NUMBER:	TI-91001
NAME OF SUBMITTER:	JACKIE MCBRIDE
SIGNATURE:	/Jackie McBride/
DATE SIGNED:	07/29/2020

Total Attachments: 3
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Application No. Attorney Docket No. TI-91001

ASSIGNMENT

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made;

WHEREAS, TEXAS INSTRUMENTS INCORPORATED, a corporation organized and existing under the laws of the State of Delaware, with a place of business at 12500 TI Boulevard, M/S 3999, Dallas, Texas 75243, is desirous of acquiring my entire right, title and interest in and to the said invention, and to the said application and any Letters Patent that may issue thereon;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign unto the said TEXAS INSTRUMENTS INCORPORATED, its successors and assigns, my entire right, title and interest in and to the said invention and in and to the said application(s) and all patents which may be granted therefor, and all divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Patent and Trademark Office to issue all patents for said invention, or patents resulting therefrom, to the said TEXAS INSTRUMENTS INCORPORATED, as assignee of my entire right, title and interest.

I also hereby sell and assign to TEXAS INSTRUMENTS INCORPORATED, its successors and assigns, my corresponding rights to the invention disclosed in said application in all other countries of the world, including the right to claim priority, file applications and obtain patents under the terms of the Paris Convention for the Protection of Industrial Property, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such rights.

I hereby further agree that I will communicate to said TEXAS INSTRUMENTS INCORPORATED, or to its successors, assigns, and legal representatives, any facts known to me respecting said invention, and at the expense of said assignee company, testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said TEXAS INSTRUMENTS INCORPORATED, its successors, assigns and nominees to obtain and enforce proper patent protection for said invention in all countries.

I authorize the later insertion of the nonprovisional application number and filing date hereinbelow.

IN WITNESS WHEREOF, I hereunto set hand and seal this day and year;

TITLE	COPPER WIRE BOND ON GOLD BUMP ON SEMICONDUCTOR DIE BOND PAD		
NONPROVISIONAL APPLICATION NO.		FILING DATE	

SIGNATURE OF INVENTOR	张林
PRINTED NAME OF INVENTOR	Lin Zhang
DATE	2020.1.8
RESIDENCE (CITY and COUNTRY)	Chengdu City, Sichuan, China

Application No.

Attorney Docket No. TI-91001

SIGNATURE OF INVENTOR	段火云
PRINTED NAME OF INVENTOR	Huo Yun Duan
DATE	2020.1.8
RESIDENCE (CITY AND COUNTRY)	Chengdu City, Sichuan, China

SIGNATURE OF INVENTOR	李喜林
PRINTED NAME OF INVENTOR	Xi Lin Li
DATE	2020.1.8
RESIDENCE (CITY AND COUNTRY)	Chengdu, Sichuan, China

SIGNATURE OF INVENTOR	熊陈
PRINTED NAME OF INVENTOR	Chen Xiong
DATE	2020.1.8
RESIDENCE (CITY AND COUNTRY)	Chengdu, Sichuan, China

Application No.

Attorney Docket No. TI-91001

SIGNATURE OF INVENTOR	康小林
PRINTED NAME OF INVENTOR	Xiao Lin Kang
DATE	2020、1、8
RESIDENCE (CITY AND COUNTRY)	Chengdu, Sichuan, China